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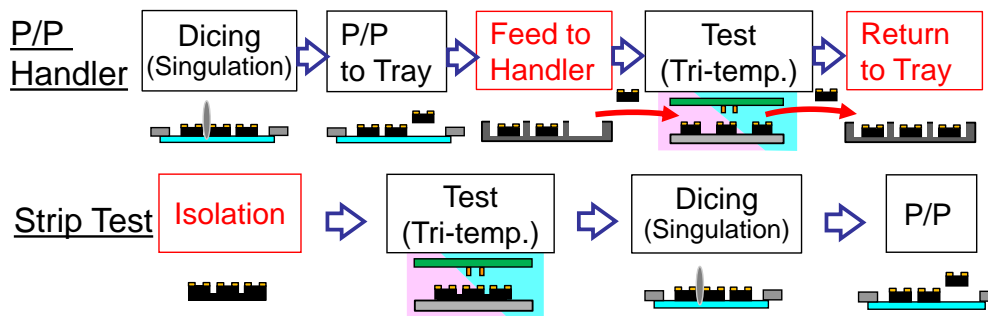
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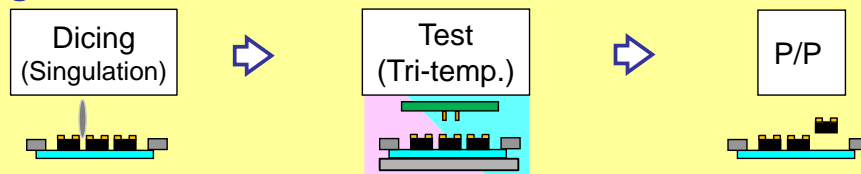
Heat/Cold Resistant Dicing Tape for Frame Handling Final Test

Eiji Hayashishita
Akimitsu Morimoto, Hideki Fukumoto,
Mitsui Chemicals Tohcello, Inc.

Introduction



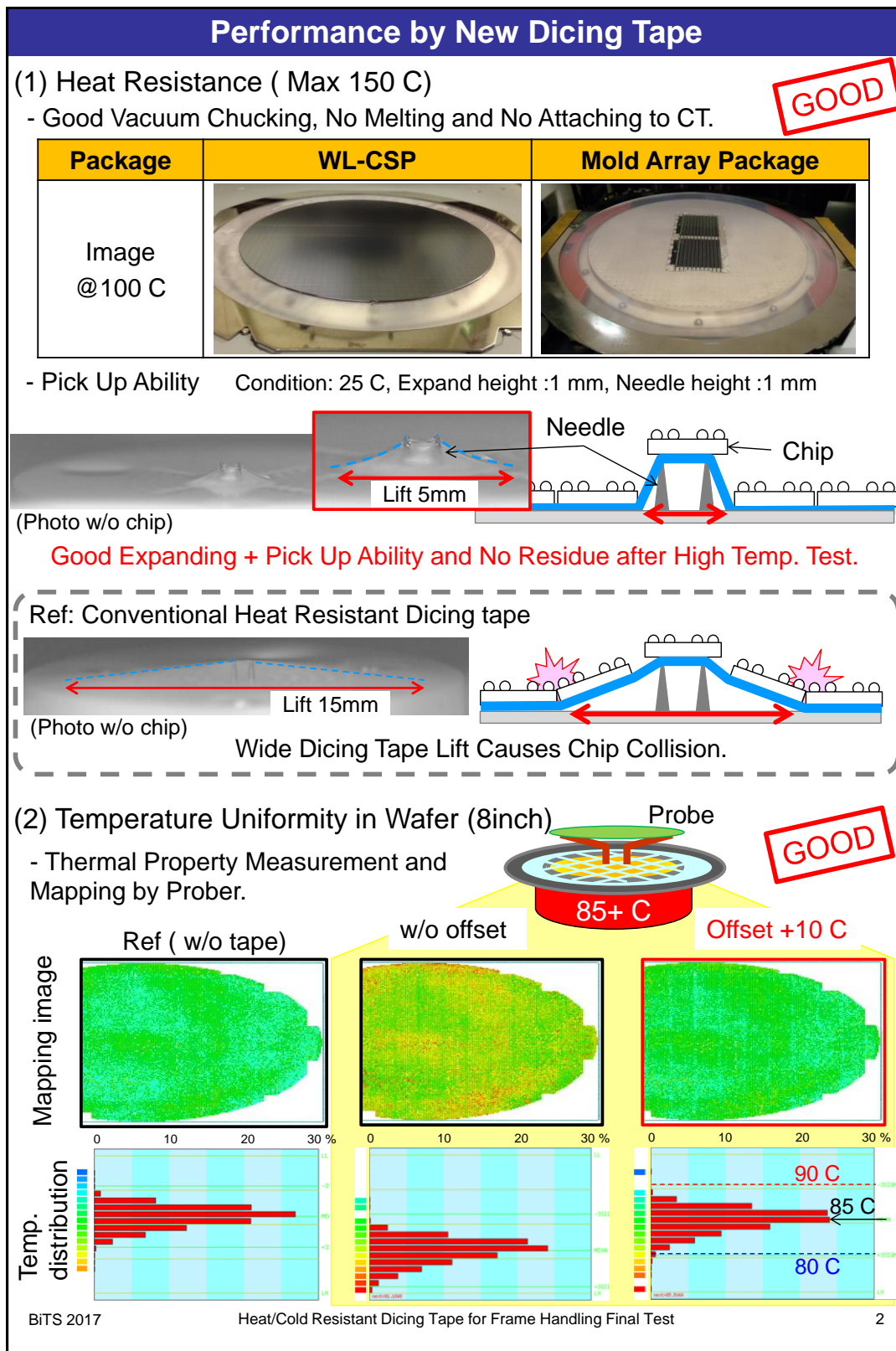
Dicing Frame Test



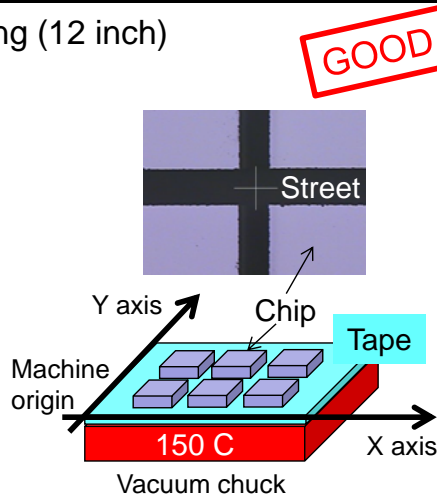
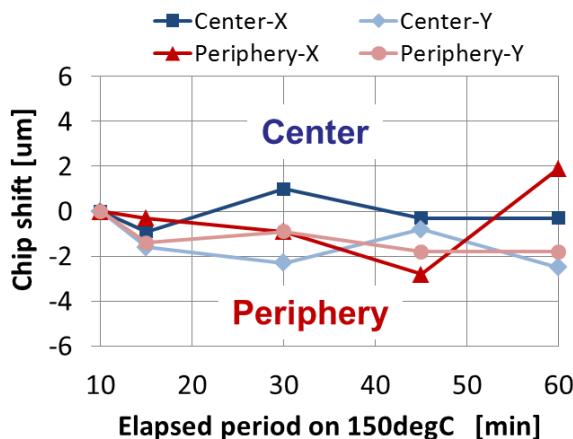
Dicing Frame Handling can reduce process step dramatically.

Method	Pros	Cons / Issues
Pick & Place (P/P) Handler	Conventional Method	Need Change Kit A lot of Package Transfer
Strip Test	Chip Position Accuracy	Need Change Kit Reliability by Not Fully Dicing
Dicing Frame Test for High Temp. Using Conventional Dicing Tape	Reduce Process Steps Test after Fully Dicing No Change Kit	Issues of Conventional Dicing Tape (1) Heat Resistance (2) Temperature Uniformity (3) Chip Position Accuracy

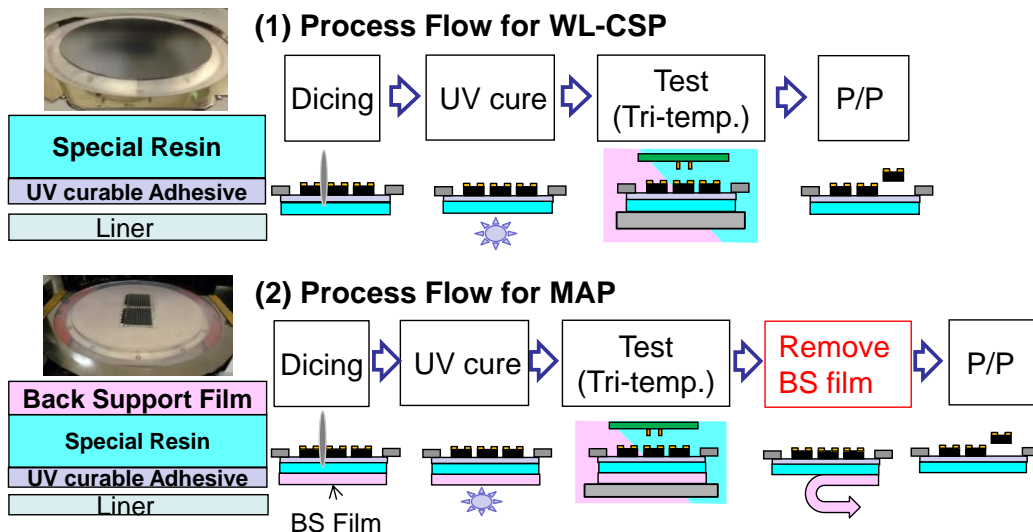
New Dicing Tape which can overcome issues of conventional tape is required.



(3) Chip Position Accuracy during Heating (12 inch)



Process Proposal



Summary

- ✓ Brand New Heat/Cold Resistant Dicing Tape which can Overcome Issues of Conventional Dicing Tape.
- ✓ Dicing Frame Handling Final Test at >85 C was actually proven successful by using H/C Resistant Dicing Tape.
- ✓ H/C Resistant Dicing Tape is designed for both WL-CSP and MAP.